Takatori
Global Innovation "Plus One"

MODEL
DTM-812X

DAF lamination wafer mounting system

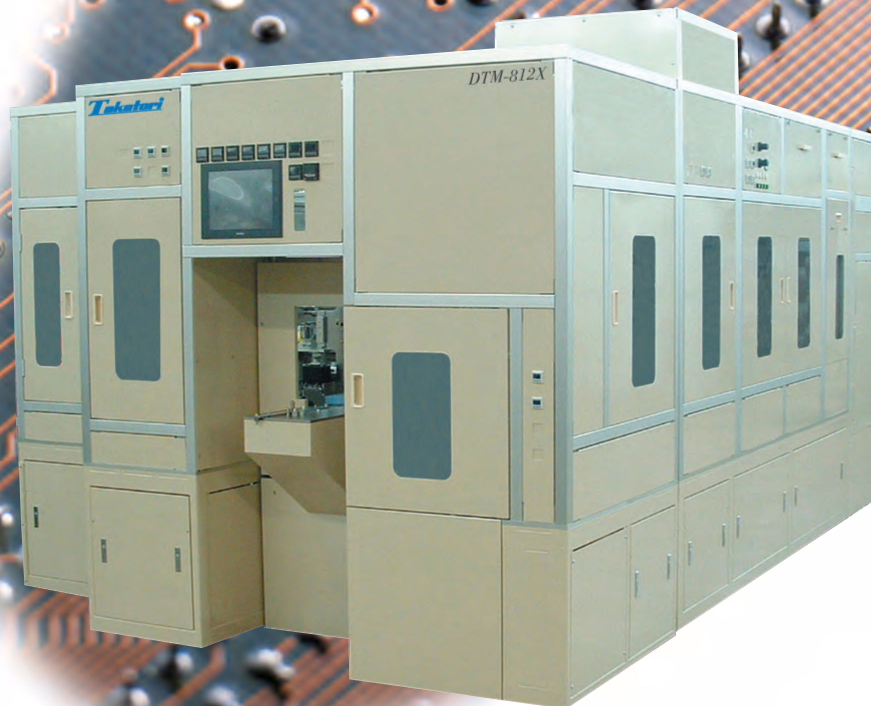
For 30μm

Outline

DTM-812X is designed to laminate one-layer DAF on 8-inch and 12-inch wafers, mount the wafers on the dicing frames, and remove the BG tape on the wafers in full automatic mode.
Either precut or type of dicing tape with DAF is applicable.
In-lining with a grinder/polisher is feasible as optional system.

Characteristics

- The footprint is smallest in the world despite the features of DAF lamination, mounting and BG tape removal.
- Standalone mode for ultra thin wafer.(Optional In-lining system with a grinder/ polisher realizes the solution to the process of more ultra thin wafer)
- Vacuum chamber system is adopted for mounting wafers on dicing tape in order to avoid bubble generation between the tape and wafers as well as to minimize extra stress on the wafer surface. Either roll or precut type of dicing tape with DAF is applicable.
- DTM-812W is also line up with DDF laminating capability.



Specification		DTM-812X
Throughput		25～30wafers/hour (aftercure : 60 sec)
Wafer Size		8 inch、12 inch
Utilities	Power	AC200V 3-phase 50／60Hz with terminal block
	Vacuum sourse	−74Kpa
	Air	Pressure 0.5Mpa
Dimensions		D 4,000 × W 2,000 × H 2,000mm
Weight		Approx 2,800kg (with UV irradiation system)

System appearance and specifications are subject to change without prior notice from the supplier.

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